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**RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE - EXAMINING GROUP 2800**

PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Box AF, Commissioner of Patents, Washington, DC 20231.

Date

December 10, 2002 SHA

Stephanie Jansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Salman Akram; Alan G. Wood;
Warren M. Farnworth

Attorney Docket No.: 500185.03

Serial No. : 09/631,900

Group Art Unit : 2827

Filed : August 4, 2000

Examiner : Lourdes C. Cruz

Title : APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED
DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER

Box AF
Commissioner of Patents
Washington, DC 20231

RESPONSE UNDER 37 C.F.R. § 1.116

Sir:

Applicants acknowledge receipt of the Office Action dated September 10, 2002.

In the Claims:

Please cancel claims 15-17 and amend claims 1 and 9 as follows:

1. (Twice Amended) A semiconductor device, comprising:
a bumped device having a plurality of conductive bumps formed thereon;

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